

2.5V - 2.6V PHASE LOCKED LOOP DIFFERENTIAL 1:10 SDRAM CLOCK DRIVER

IDTCSPT857D

FFATURFS:

- · 1 to 10 differential clock distribution
- Optimized for clock distribution in DDR (Double Data Rate) SDRAM applications requiring improved output crosspoint voltage
- · Operating frequency: 60MHz to 220MHz
- · Very low skew:
 - <100ps for PC1600 PC2700
 - <75ps for PC3200
- · Very low jitter:
 - <75ps for PC1600 PC2700</p>
 - <50ps for PC3200
- 2.5V AVDD and 2.5V VDDQ for PC1600-PC2700
- 2.6V AVDD and 2.6V VDDQ for PC3200
- · CMOS control signal input
- Test mode enables buffers while disabling PLL
- · Low current power-down mode
- Tolerant of Spread Spectrum input clock
- Available in 48-pin TSSOP, 40-pin VFQFPN, and 56-pin VFBGA packages

APPLICATIONS:

- Meets or exceeds JEDEC standard JESD 82-1A for registered DDR clock driver
- · Meets proposed DDR1-400 specification
- For all DDR1 speeds: PC1600 (DDR200), PC2100 (DDR266), PC2700 (DDR333), PC3200 (DDR400)
- Along with SSTV16857, SSTVF16857, SSTV16859, SSTVM16859, SSTVF16859, SSTVN16859, DDR1 register, provides complete solution for DDR1 DIMMs

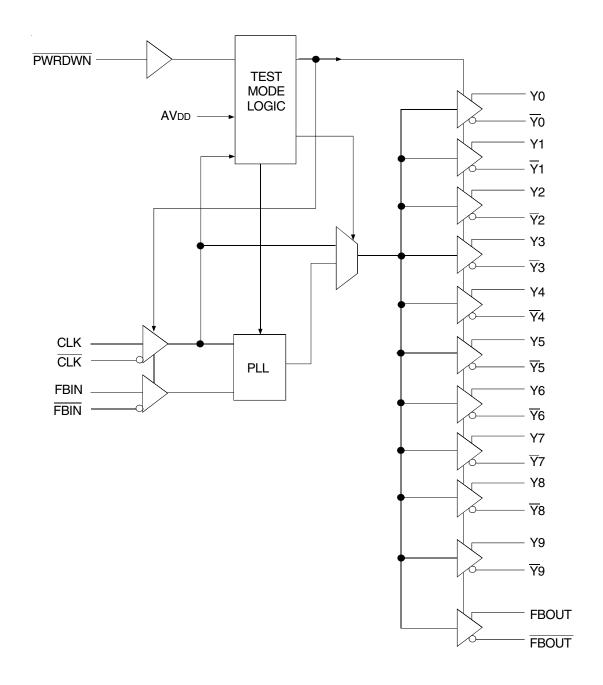
DESCRIPTION:

The CSPT857D is a PLL based clock driver that acts as a zero delay buffer to distribute one differential clock input pair (CLK, $\overline{\text{CLK}}$) to 10 differential output pairs (Y [0:9], $\overline{\text{Y}}$ [0:9]) and one differential pair of feedback clock output (FBOUT, $\overline{\text{FBOUT}}$). External feedback pins (FBIN, $\overline{\text{FBIN}}$) for synchronization of the outputs to the input reference is provided. A CMOS Enable/Disable pin is available for low power disable. When the input frequency falls below approximately 20MHz, the device will enter power down mode. In this mode, the receivers are disabled, the PLL is turned off, and the output clock drivers are tristated, resulting in a current consumption of less than 200µA.

The CSPT857D requires no external components and has been optimised for very low I/O phase error, skew, and jitter, while maintaining frequency and duty cycle over the operating voltage and temperature range. The CSPT857D, designed for use in both module assemblies and system motherboard based solutions, provides an optimum high-performance clock source.

The CSPT857D is available in Commercial Temperature Range (0 $^{\circ}$ C to +70 $^{\circ}$ C). See Ordering Information for details.

FUNCTIONAL BLOCK DIAGRAM

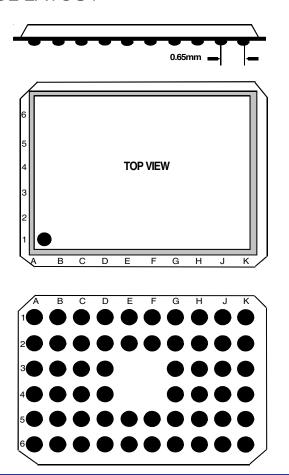


PIN CONFIGURATIONS

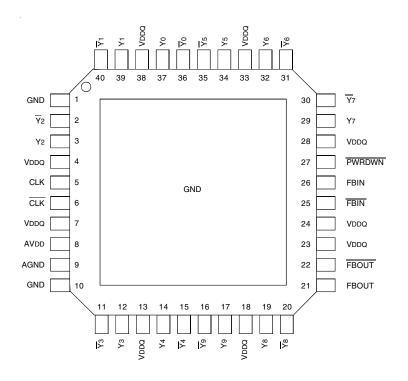
			T			ı				
6	Y 5	<u>Y6</u>	GND	Y 7	PWR DWN	FBIN	VDDQ	FBOUT	<u>Y</u> 8	Y 9
5	<u>Y</u> 5	Y 6	GND	Y 7	VDDQ	FBIN	FBOUT	GND	Y 8	<u>Y9</u>
4	GND	VDDQ	NC	NC			NC	NC	VDDQ	GND
3	GND	VDDQ	NC	NC			NC	NC	VDDQ	GND
2	<u>Y0</u>	Y1	GND	<u>Y2</u>	VDDQ	CLK	AVDD	GND	Y 3	<u>Y4</u>
1	Y0	<u>Y</u> 1	GND	Y 2	VDDQ	CLK	VDDQ	AGND	<u>Y</u> 3	Y4
	Α	В	С	D	Е	F	G	Н	J	K

VFBGA TOP VIEW

56 BALL VFBGA PACKAGE LAYOUT



PIN CONFIGURATIONS



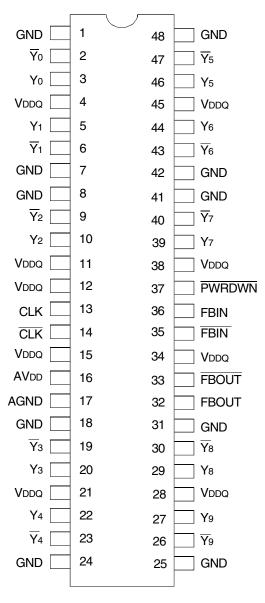
VFQFPN TOP VIEW

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Rating	Max	Unit
Vddq, AVdd	Supply Voltage Range	-0.5 to +3.6	V
VI ⁽²⁾	Input Voltage Range	-0.5 to V _{DDQ} + 0.5	V
Vo ⁽²⁾	Voltage range applied to any	-0.5 to VDDQ + 0.5	V
	output in the high or low state		
lik	Input Clamp Current	-50	mA
(VI <0)			
Іок	Output Clamp Current	±50	mA
(Vo <0 or			
Vo > Vddq)			
lo	Continuous Output Current	±50	mA
(Vo =0 to VDDQ)			
VDDQ or GND	Continuous Current	±100	mA
TSTG	Storage Temperature Range	- 65 to +150	°C

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause
 permanent damage to the device. This is a stress rating only and functional operation
 of the device at these or any other conditions above those indicated in the operational
 sections of this specification is not implied. Exposure to absolute maximum rating
 conditions for extended periods may affect reliability.
- The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.



TSSOP TOP VIEW

CAPACITANCE(1)

Parameter Description		Min.	Тур.	Max.	Unit
CIN	Input Capacitance	2.5	_	3.5	pF
	VI = VDDQ or GND				
CI(Δ)	Delta Input Capacitance	-0.25	_	0.25	pF
	VI = VDDQ or GND				
CL	Load Capacitance	_	14	_	pF

NOTE:

1. Unused inputs must be held high or low to prevent them from floating.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min.	Тур.	Max.	Unit
AVDD	Supply Voltage		VDDQ-0.12	VDDQ	2.7	V
VDDQ	I/O Supply Voltage	PC1600-PC2700	2.3	2.5	2.7	V
		PC3200	2.5	2.6	2.7	
TA	Operating Free-Air Temperature		0	_	+70	°C

PIN DESCRIPTION (TSSOP/TVSOP)

Pin Name	Pin Number	Description
AGND	17	Ground for analog supply
AVDD	16	Analog supply
CLK, CLK	13,14	Differential clock input
FBIN, FBIN	35,36	Feedback differential clock input
FBOUT, FBOUT	32,33	Feedback differential clock output
GND	1, 7, 8, 18, 24, 25, 31, 41, 42, 48	Ground
PWRDWN	37	Output enable for Y and \overline{Y}
VDDQ	4, 11, 12, 15, 21, 28, 34, 38, 45	I/O supply
Y[0:9]	3, 5, 10, 20, 22, 27, 29, 39, 44, 46	Buffered output of input clock, CLK
Y[0:9]	2, 6, 9, 19, 23, 26, 30, 40, 43, 47	Buffered output of input clock, CLK

PIN DESCRIPTION (VFBGA)

Pin Name	Pin Number	Description
AGND	H1	Ground for analog supply
AVDD	G2	Analog supply
CLK, CLK	F1, F2	Differential clock input
FBIN, FBIN	F5, F6	Feedback differential clock input
FBOUT, FBOUT	H6, G5	Feedback differential clock output
GND	A3, A4, C1, C2, C5, C6, H2, H5, K3, K4	Ground
PWRDWN	E6	Output enable for Y and \overline{Y}
VDDQ	B3, B4, E1, E2, E5, G1, G6, J3, J4	I/O supply
Y[0:9]	A1, A6, B2, B5, D1, D6, J2, J5, K1, K6	Buffered output of input clock, CLK
Y[0:9]	A2, A5, B1, B6, D2, D5, J1, J6, K2, K5	Buffered output of input clock, CLK

PIN DESCRIPTION (VFQFPN)

Pin Name	Pin Number	Description
AGND	9	Ground for analog supply
AVDD	8	Analog supply
CLK, CLK	5, 6	Differential clock input
FBIN, FBIN	25,26	Feedback differential clock input
FBOUT, FBOUT	21,22	Feedback differential clock output
GND	1, 10	Ground
PWRDWN	27	Output enable for Y and \overline{Y}
VDDQ	4, 7, 13, 18, 23, 24, 28, 33, 38	I/O supply
Y[0:9]	3, 12, 14, 17, 19, 29, 32, 34, 37, 39	Buffered output of input clock, CLK
Y[0:9]	2, 11, 15, 16, 20, 30, 31, 35, 36, 40	Buffered output of input clock, CLK

FUNCTION TABLE(1)

INPUTS				OUTPUTS				
AVDD	PWRDWN	CLK	CLK	Υ	Ÿ	FBOUT	FBOUT	PLL
GND	Н	L	Н	L	Н	L	Н	Bypassed/OFF
GND	Н	Н	L	Н	L	Н	L	Bypassed/OFF
Х	L	L	Н	Z	Z	Z	Z	OFF
Х	L	Н	L	Z	Z	Z	Z	OFF
Nominal ⁽²⁾	Н	L	Н	L	Н	L	Н	ON
Nominal ⁽²⁾	Н	Н	L	Н	L	Н	L	ON
Nominal ^(2,3)	Х	<20MHz	<20MHz	Z	Z	Z	Z	OFF

NOTES:

- 1. H = HIGH Voltage Level
 - L = LOW Voltage Level
 - Z = High-Impedance OFF-State
 - X = Don't Care
- 2. AVDD nominal is 2.5V for PC1600, PC2100, and PC2700. AVDD nominal is 2.6V for PC3200.
- 3. Additional feature that senses when the clock input is less than approximately 20MHz and places the part in sleep mode. Reciever inputs and PLL are turned off and outputs = tristate.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE FOR PC1600 - PC2700

Following Conditions Apply Unless Otherwise Specified:

Commercial: $TA = 0^{\circ}C$ to $+70^{\circ}C$

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Vik	Input Clamp Voltage (All Inputs)	VDDQ = 2.3V, II = -18mA	_	_	-1.2	V
VIL (dc)	Static Input LOW Voltage	PWRDWN	-0.3	_	0.7	V
VIH (dc)	Static Input HIGH Voltage	PWRDWN	1.7	_	VDDQ + 0.3	
VIL (ac)	Dynamic Input LOW Voltage	CLK, CLK, FBIN, FBIN	_	_	0.7	V
VIH (ac)	Dynamic Input HIGH Voltage	CLK, CLK, FBIN, FBIN	1.7		VDDQ	
Vol	Output LOW Voltage	AVDD/VDDQ = Min., IOL = 100μ A	_		0.1	V
		AVDD/VDDQ = Min., IOL = 12mA	_		0.6	
Vон	Output HIGH Voltage	AVDD/VDDQ = Min., IOH = -100μ A	VDDQ - 0.1			V
		AVDD/VDDQ = Min., IOH = -12mA	1.7			
Vıx	Input Differential Cross Voltage		VDDQ/2-0.2		VDDQ/2 + 0.2	V
VID(DC) ⁽¹⁾	DC Input Differential Voltage		0.36		VDDQ + 0.6	V
VID(AC) ⁽¹⁾	AC Input Differential Voltage		0.7		VDDQ + 0.6	V
lin	Input Current	VDDQ = 2.7V, $VI = 0V$ to $2.7V$			±10	μΑ
IDDPD	Power-Down Current on VDDQ and AVDD	AVDD/VDDQ = Max., CLK = $0MHz$ or \overline{PWRDWN} = L	_	100	200	μΑ
IDDQ	Dynamic Power Supply Current on VDDQ	AVDD/VDDQ = Max., CLK = 200MHz, $120\Omega/14pF$	_	320	360	mA
		AVDD/VDDQ = Max., CLK = 170MHz, $120\Omega/14pF$	_	250	300	
ladd	Dynamic Power Supply Current on AVDD	AVDD/VDDQ = Max., CLK = 170MHz	_		12	mA

NOTE:

1. $\overline{\text{VID}}$ is the magnitude of the difference between the input level on $\overline{\text{CLK}}$.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE FOR PC3200

Following Conditions Apply Unless Otherwise Specified:

Commercial: $TA = 0^{\circ}C$ to $+70^{\circ}C$

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Vik	Input Clamp Voltage (All Inputs)	VDDQ = 2.5V, II = -18mA	_	_	-1.2	V
VIL(dc)	Static Input LOW Voltage	PWRDWN	-0.3	_	0.7	V
VIH (dc)	Static Input HIGH Voltage	PWRDWN	1.7	_	VDDQ + 0.3	
VIL(ac)	Dynamic Input LOW Voltage	CLK, CLK, FBIN, FBIN	_	_	0.7	V
VIH (ac)	Dynamic Input HIGH Voltage	CLK, CLK, FBIN, FBIN	1.7		VDDQ	
Vol	Output LOW Voltage	AVDD/VDDQ = Min., IOL = 100μ A	_		0.1	V
		AVDD/VDDQ = Min., IOL = 12mA	_		0.6	
Vон	Output HIGH Voltage	AVDD/VDDQ = Min., IOH = -100μ A	VDDQ - 0.1			V
		AVDD/VDDQ = Min., IOH = -12mA	1.7			
Vıx	Input Differential Cross Voltage		VDDQ/2-0.2		VDDQ/2 + 0.2	V
VID(DC) ⁽¹⁾	DC Input Differential Voltage		0.36		VDDQ + 0.6	V
VID(AC) ⁽¹⁾	AC Input Differential Voltage		0.7		VDDQ + 0.6	V
lin	Input Current	VDDQ = 2.7V, VI = 0V to 2.7V			±10	μΑ
IDDPD	Power-Down Current on VDDQ and AVDD	AVDD/VDDQ = Max., CLK = $0MHz$ or \overline{PWRDWN} = L	_	100	200	μΑ
IDDQ	Dynamic Power Supply Current on VDDQ	AVDD/VDDQ = Max., CLK = 200MHz, $120\Omega/14pF$	_	320	360	mA
		AVDD/VDDQ = Max., CLK = 200MHz, $120\Omega/14pF$	_	250	300	
IADD	Dynamic Power Supply Current on AVDD	AVDD/VDDQ = Max., CLK = 200MHz	_	·	12	mA

NOTE:

TIMING REQUIREMENTS FOR PC1600 - PC2700

Symbol	Parameter	Min.	Max.	Unit
fclk	Operating Clock Frequency ^(1,2)	60	200	MHz
	Application Clock Frequency ^(1,3)	60	200	MHz
toc	Input Clock Duty Cycle	40	60	%
t _L	Stabilization Time ⁽⁴⁾		100	μs

NOTES:

- 1. The PLL will track a spread spectrum clock input.
- 2. Operating clock frequency is the range over which the PLL will lock, but may not meet all timing specifications.
- 3. Application clock frequency is the range over which timing specifications apply.
- 4. Stabilization time is the time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal after power up.

TIMING REQUIREMENTS FOR PC3200

Symbol	Parameter	Min.	Max.	Unit
fclk	Operating Clock Frequency ^(1,2)	60	220	MHz
	Application Clock Frequency ^(1,3)	60	220	MHz
toc	Input Clock Duty Cycle	40	60	%
t_	Stabilization Time ⁽⁴⁾	_	100	μs

NOTES:

- 1. The PLL will track a spread spectrum clock input.
- 2. Operating clock frequency is the range over which the PLL will lock, but may not meet all timing specifications.
- 3. Application clock frequency is the range over which timing specifications apply.
- 4. Stabilization time is the time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal after power up.

^{1.} VID is the magnitude of the difference between the input level on CLK and the input level on $\overline{\text{CLK}}$.

SWITCHING CHARACTERISTICS FOR PC1600 - PC2700

Symbol	Description	Test Conditions	Min.	Typ. ⁽¹⁾	Max.	Unit
tPLH ⁽¹⁾	LOW to HIGH Level Propagation Delay Time	Test mode, CLK to any output		4.5		ns
tPHL ⁽¹⁾	HIGH to LOW Level Propagation Delay Time	Test mode, CLK to any output		4.5		ns
UIT(PER)	Jitter (period), see figure 6	66MHz	-90		90	ps
		100/ 133/ 167/ 200 MHz	-75		75]
t/IT(CC)	Jitter (cycle-to-cycle), see figure 3	66MHz	-180		180	ps
		100/ 133/ 167/ 200 MHz	-75		75	1
UIT(HPER)	Half-Period Jitter, see figure 7	66MHz	-160		160	ps
		100/ 133/ 167/ 200 MHz	-100		100]
tslr(0)	Output Clock Slew Rate (Single-Ended)	100/ 133/ 167/ 200 MHz (20% to 80%)	1		2.5	V/ns
tslr(1)	Input Clock Slew Rate		1		4	V/ns
t(∅)	Static Phase Offset, see figure 4 ^(2,3)	66/ 100/ 133/ 167/ 200 MHz	-50		50	ps
tsk(o)	Output Skew, see figure 5				75	ps
tr,tf	Output Rise and Fall Times (20% to 80%)	Load: 120Ω / 14pF	650		900	ps
Vox ⁽⁵⁾	Output Differential Voltage	Differential outputs are terminated	VDDQ/2		VDDQ/2	V
		with 120 Ω	-0.15		+ 0.15	
The PLL on	the CSPT857D will meet all the above test parame	ters while supporting SSC synthesizers ⁽⁴⁾ w	ith the following pa	arameters:		•
SSC	Modulation Frequency	_	30	_	50	KHz
SSC	Clock Input Frequency Deviation	_	0	_	-0.5	%
f3dB	PLL Loop Bandwidth	_	_	5	_	MHz

NOTES:

- 1. Refers to transition of non-inverting output.
- 2. Static phase offset does not include jitter.
- 3. t(φ) is measured with input clock slew rate tslR(ı) = 2V/ns and an input differential voltage ViD of 1.75V.
- 4. The SSC requirements meet the Intel PC100 SDRAM Registered DIMM specification.
- 5. Vox is specified at the SDRAM clock input or test load.

SWITCHING CHARACTERISTICS FOR PC3200

Symbol	Description	Test Conditions	Min.	Typ. ⁽¹⁾	Max.	Unit
tPLH ⁽¹⁾	LOW to HIGH Level Propagation Delay Time	Test mode, CLK to any output		4.5		ns
t _{PHL} (1)	HIGH to LOW Level Propagation Delay Time	Test mode, CLK to any output		4.5		ns
tjit(per)	Jitter (period), see figure 6	66MHz	-90		90	ps
		200 MHz	-50		50	
UIT(CC)	Jitter (cycle-to-cycle), see figure 3	66MHz	-180		180	ps
		200 MHz	- 75		75	1
tjit(HPER)	Half-Period Jitter, see figure 7	66MHz	-160		160	ps
		200 MHz	- 75		75	1
tslr(0)	Output Clock Slew Rate (Single-Ended)	200 MHz (20% to 80%)	1		2.5	V/ns
tslr(1)	Input Clock Slew Rate		1		4	V/ns
t(∅)	Static Phase Offset, see figure 4 ^(2,3)	200 MHz	-50		50	ps
tsk(o)	Output Skew, see figure 5				75	ps
tr,tf	Output Rise and Fall Times (20% to 80%)	Load: 120Ω / 14pF	650		900	ps
Vox ⁽⁵⁾	Output Differential Voltage	Differential outputs are terminated	VDDQ/2		VDDQ/2	V
		with 120Ω	-0.15		+ 0.15	
The PLL on	the CSPT857D will meet all the above test parame	ters while supporting SSC synthesizers ⁽⁴⁾ v	vith the following pa	arameters:		•
SSC	Modulation Frequency	_	30	_	50	KHz
SSC	Clock Input Frequency Deviation	_	0	_	-0.5	%
f3dB	PLL Loop Bandwidth	_	_	5	_	MHz

NOTES:

- 1. Refers to transition of non-inverting output.
- Static phase offset does not include jitter.
 t(φ) is measured with input clock slew rate tslR(I) = 2V/ns and an input differential voltage VID of 1.75V.
- 4. The SSC requirements meet the Intel PC100 SDRAM Registered DIMM specification.
- 5. Vox is specified at the SDRAM clock input or test load.

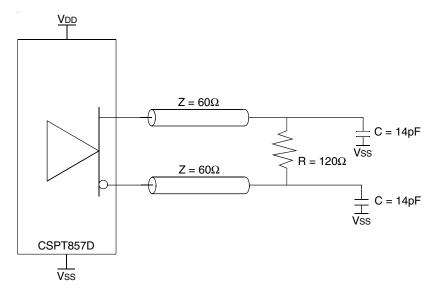


Figure 1. Output Load

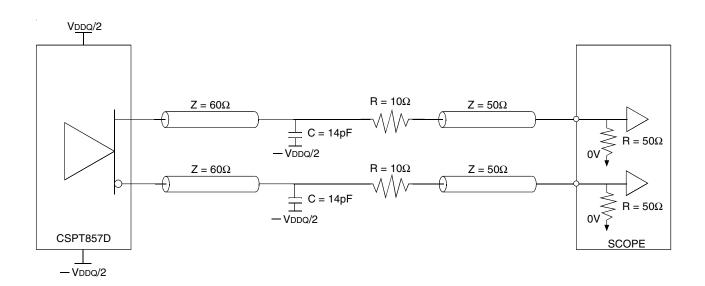
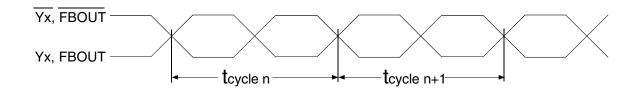
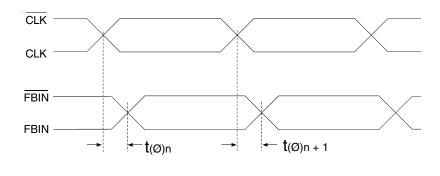


Figure 2. Output Load Test Circuit



$$t_{jit(cc)} = t_{cycle n} - t_{cycle n+1}$$

Figure 3. Cycle-to-Cycle jitter



$$t_{(\emptyset)} = \frac{\sum_{1}^{n = N} t_{(\emptyset)n}}{N}$$

(N is a large number of samples)

Figure 4. Static Phase Offset

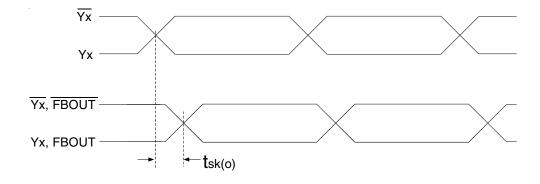
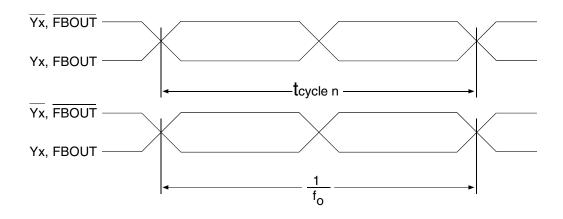


Figure 5. Output Skew



$$t_{jit(per)} = t_{cycle n} - \frac{1}{f_o}$$

Figure 6. Period jitter

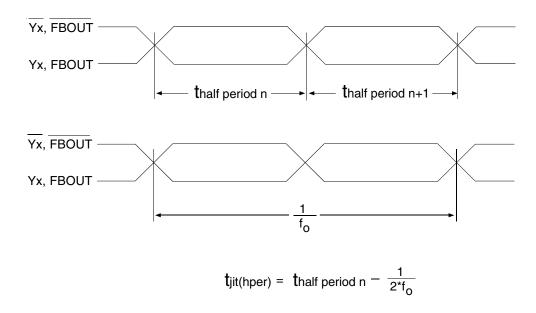


Figure 7. Half-Period jitter



Figure 8. Input and Output Slew Rates

APPLICATION INFORMATION

		Clock Loading on the PLL outputs (pF)	
Clock Structure	# of SDRAM Loads per Clock	Min.	Мах.
#1	2	4	7
#2	4	8	14

APPLICATION INFORMATION

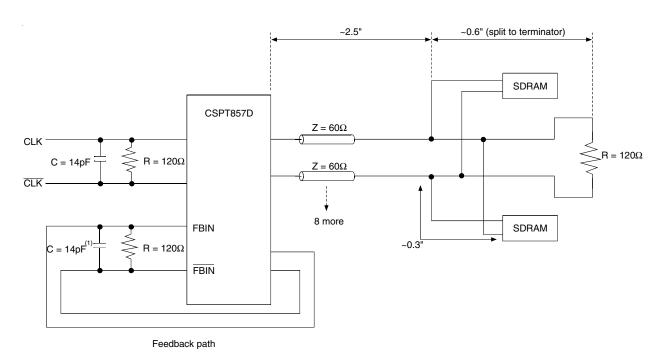


Figure 9. Clock Structure 1

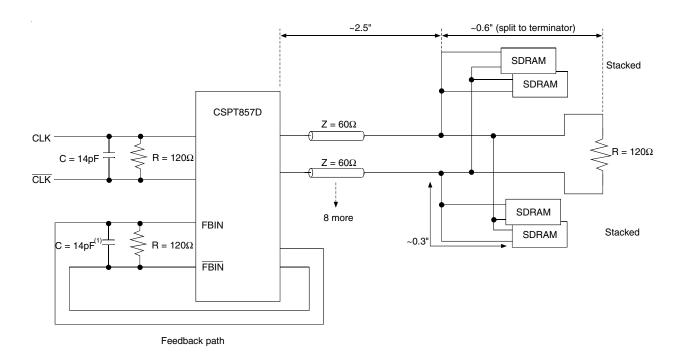
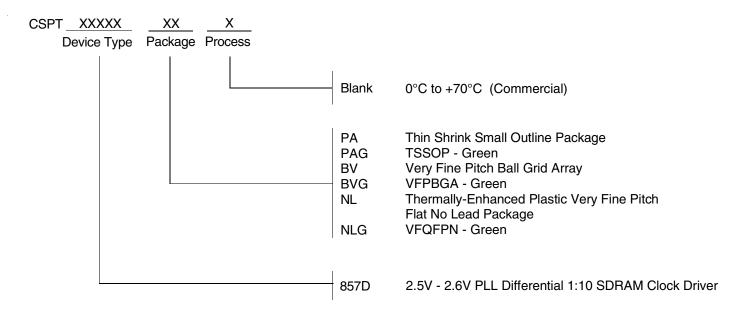


Figure 10. Clock Structure 2

NOTE:

1. Memory module vendors may need to adjust the feedback capacitive load in order to meet DDR SDRAM registered DIMM timing requirements.

ORDERING INFORMATION



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